/ Descriptions

TO-220F

Schottky Diode in a TO-220F Plastic Package.

/ Features

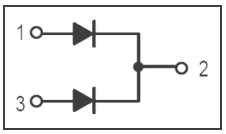
Low forward voltage drop,low power losses,High efficiency operation.

/ Applications

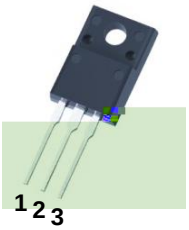
OR-ing DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

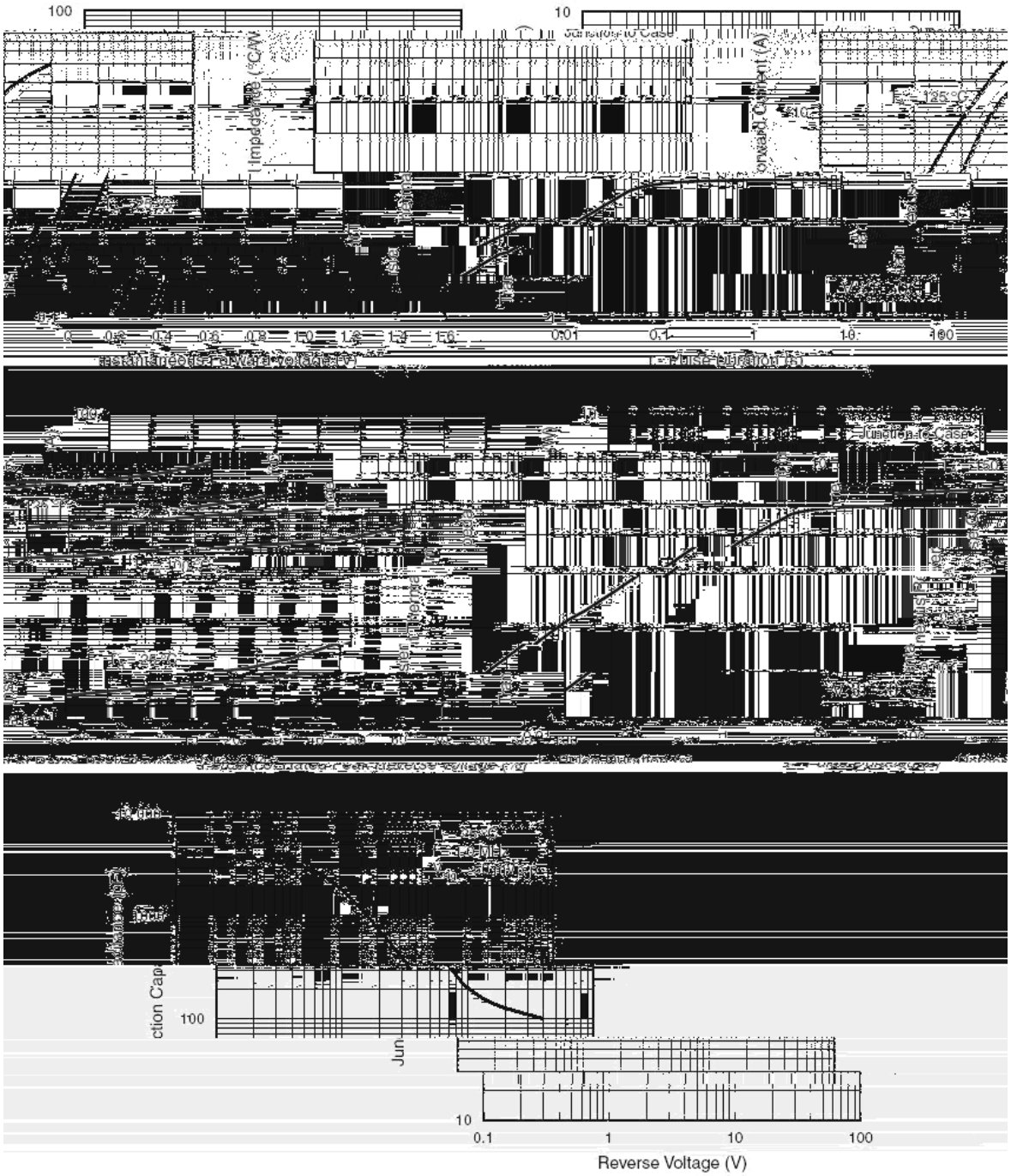
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Voltage	V_{RMS}	105	V
Average Rectified Forward Current(total)	$I_{F(AV)}$	2×15	A
Non Repetitive Peak Surge Current	I_{FSM}	250	A
Thermal Resistance Junction to Case	R_{Jc}	4.6	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

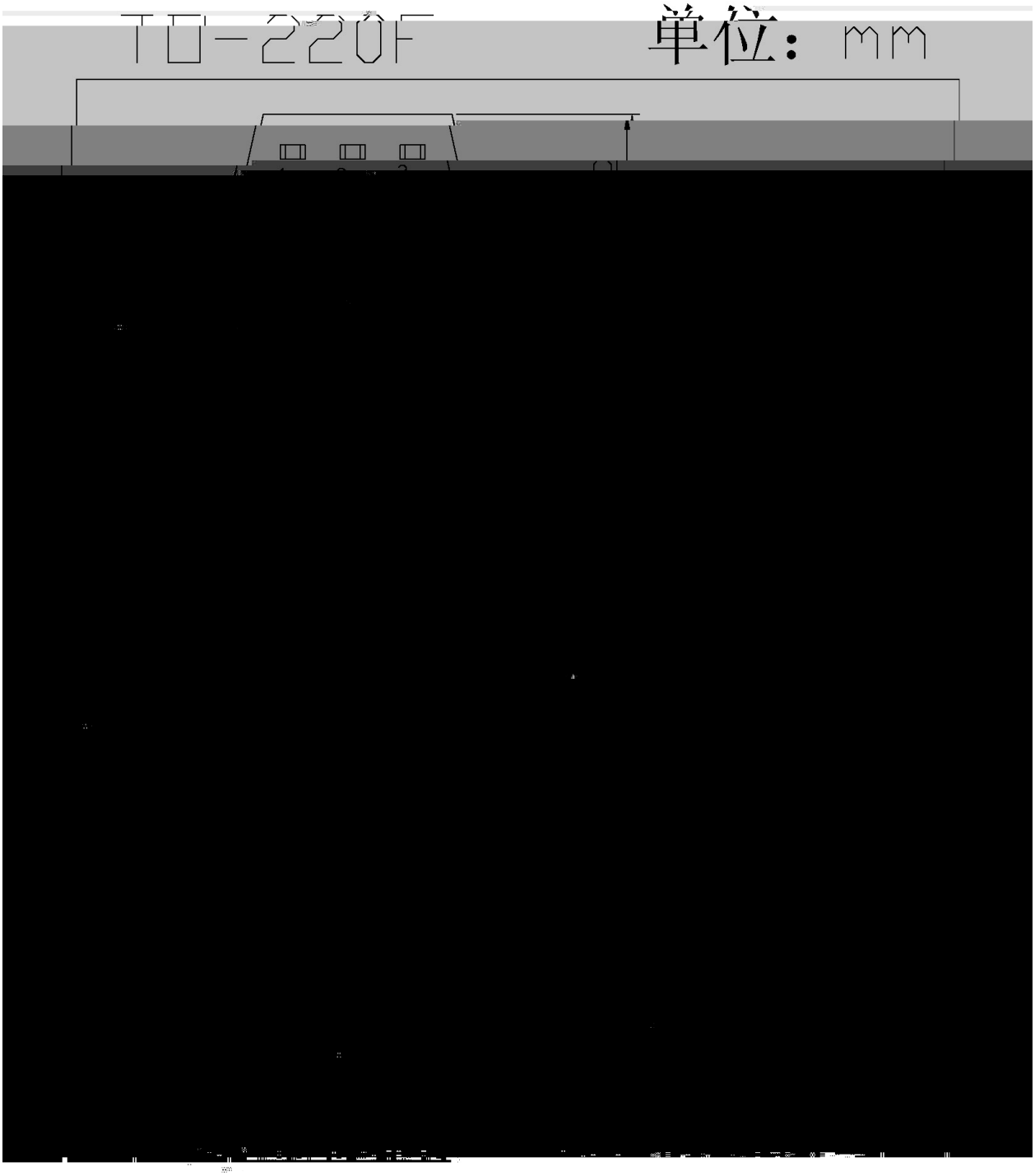
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_{BR}	I_R=1mA(Ta=25)	150			V

/3998 18.478())]TJ/TT 1refV.3(V5 402.328 452.2.328 13-00013 Tc0.00307.02 0 0 7.5 292.32 453.8003 T400140013 T

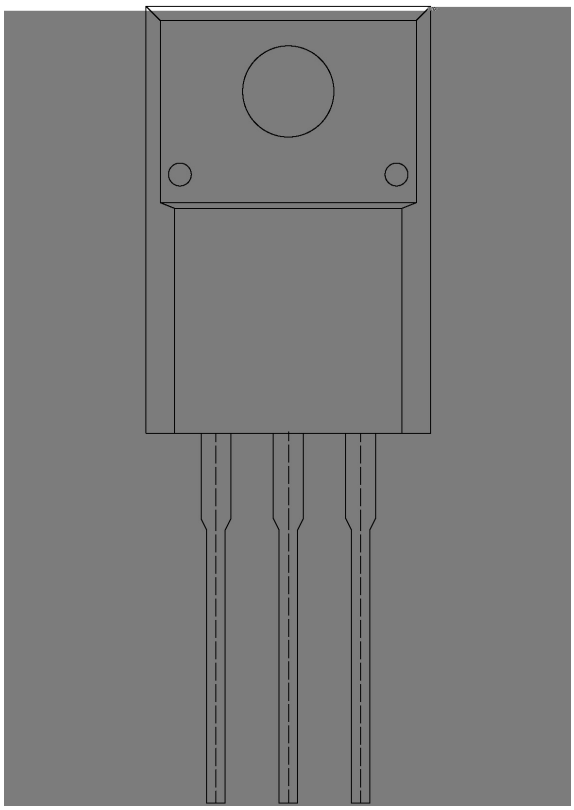
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



BR

LV30150

F:

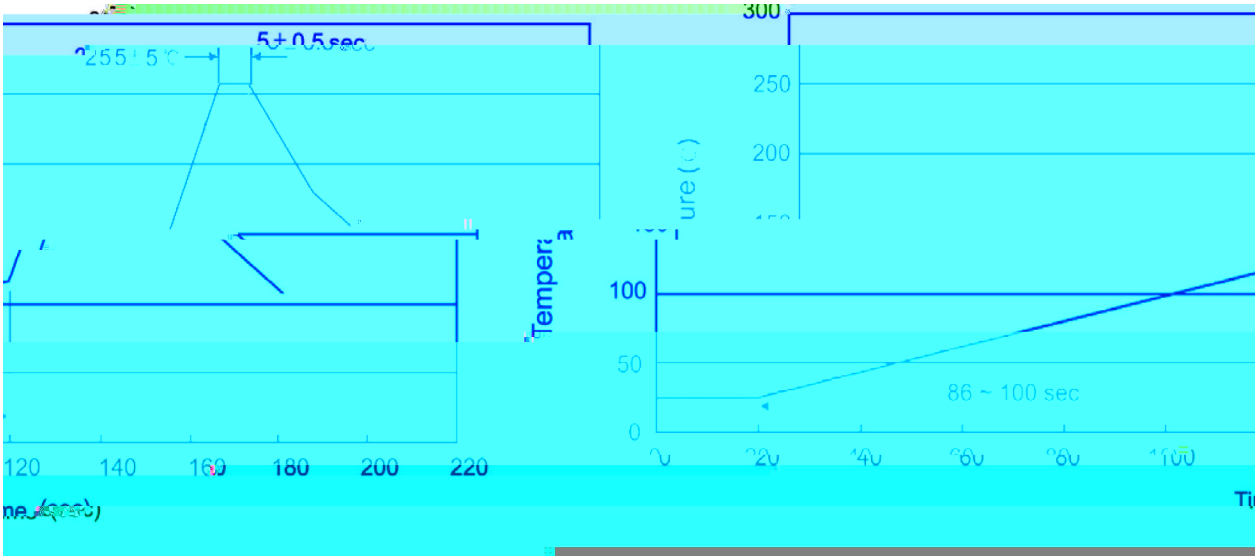
CT:

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Note:

BR: Company Code

( ) / Temperature Profile for Dip Soldering(Pb-Free)



					Note:
1		25	150	60	90sec;
2		255±5			5±0.5sec;
3			2	10	/sec.

Note:
1.Preheating:25~150 , Time:60~90sec.
2.Peak Temp.:255±5 , Duration:5±0.5sec.
3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension		(unit mm^3)

/ TUBE

Package Type	Units					Dimension		(unit mm^3)

/ Notices